

20th Anniversary of KSDT
KISM 2022
Korean International Semiconductor Conference on Manufacturing Technology 2022
November 13-16, 2022 | Paradise Hotel Busan (Haeundae Beach), Busan, Korea

Session Title:	[TE3] 3D Integration/Process
Session Date:	November 15 (Tue.), 2022
Session Time:	14:30-16:00
Session Room:	Room E (Grand Ballroom 3, 2F)
Session Chair:	Prof. Hyun Yong Yu (Korea Univ., Korea)

[TE3-1] [Invited] 14:30-15:00

3-Dimensional Integration with High Interconnection Density

Rino Choi, Ye-eun Hong, and Anh Duy Nguyen (Inha Univ., Korea)

[TE3-2] 15:00-15:20

Monolithic 3D InGaAs HEMT for Future Communication and Quantum Computing

Sanghyeon Kim, Jaeyong Jeong (KAIST, Korea), and Jongmin Kim (KANC, Korea)

[TE3-3] 15:20-15:40

Space-Confined High-Temperature Heat Treatment Process for 3D Integration Compatibility

Hyuk-Jun Kwon (DGIST, Korea)

[TE3-4] 15:40-16:00

3D Integration Using Wafer Layer Transfer Technology

Changhwan Choi (Hanyang Univ., Korea)